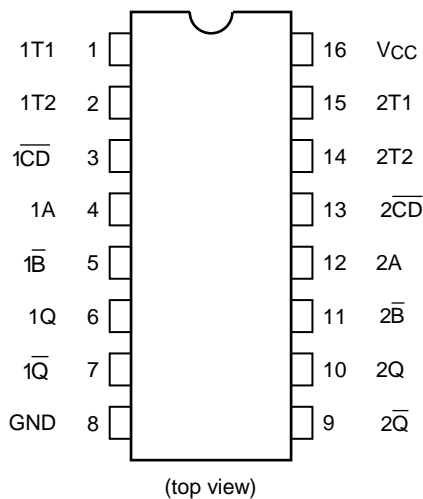
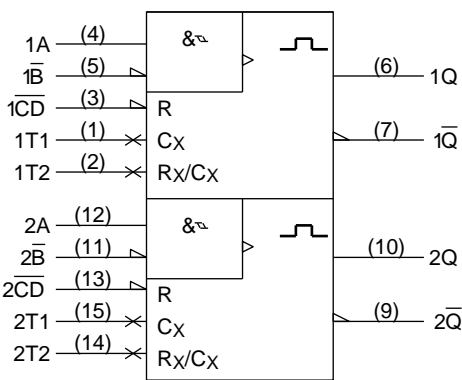


Pin Assignment



IEC Logic Symbol

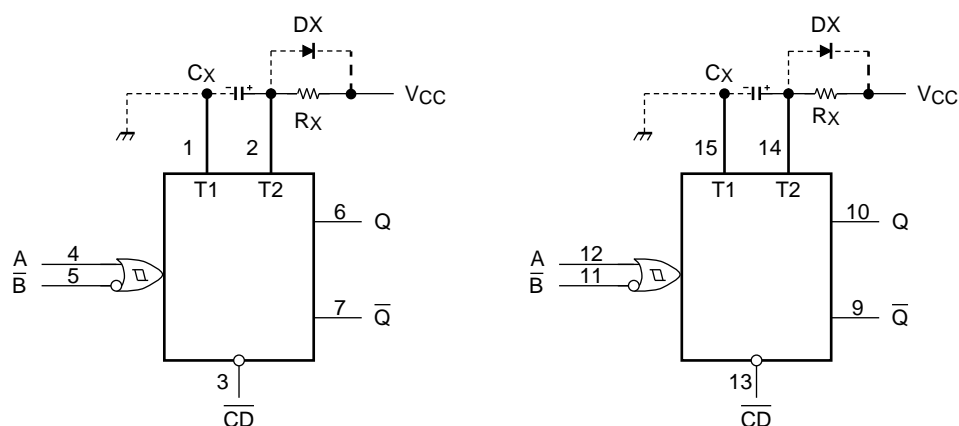


Truth Table

Inputs			Outputs		Note
A	B	CD	Q	Q	
	H	H			Output Enable
X	L	H	L	H	Inhibit
H	X	H	L	H	Inhibit
L		H			Output Enable
X	X	L	L	H	Reset

X: Don't care

Block Diagram (Note)



Note: CX, RX, DX are external capacitor, resistor, and diode, respectively.

Note: External clamping diode, DX

The external capacitor is charged to VCC level in the wait state, i.e. when no trigger is applied. Supply voltage is turned off and CX is discharged mainly through the internal (parasitic) diode. If CX is sufficiently large and VCC drops rapidly, there will be some possibility of damaging the IC by rush current or latch-up. If the capacitance of the supply voltage filter is large enough and VCC drops slowly, the rush current is automatically limited and damage to the IC is avoided.

The maximum value of forward current through the parasitic diode is ± 20 mA.

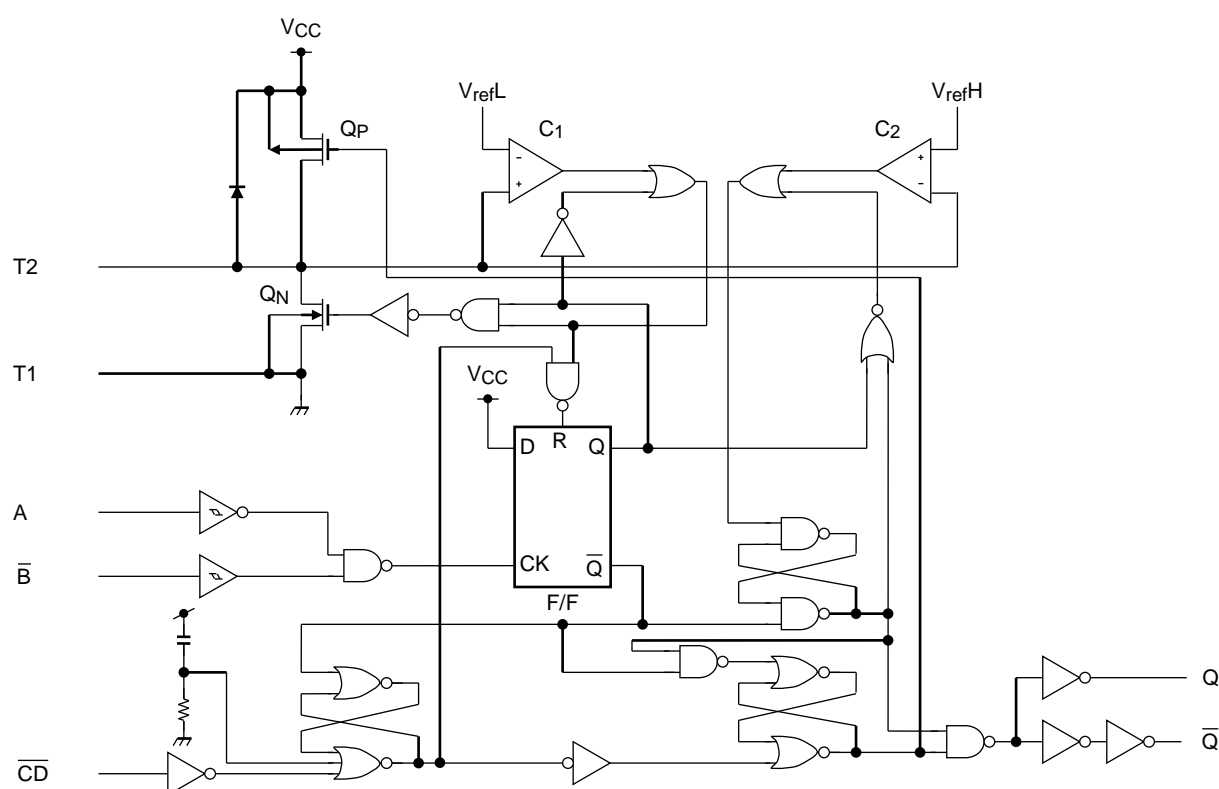
In the case of a large CX, the limitation of fall time of the supply voltage is determined as follows:

$$t_f \geq (V_{CC} - 0.7) C_X / 20 \text{ mA}$$

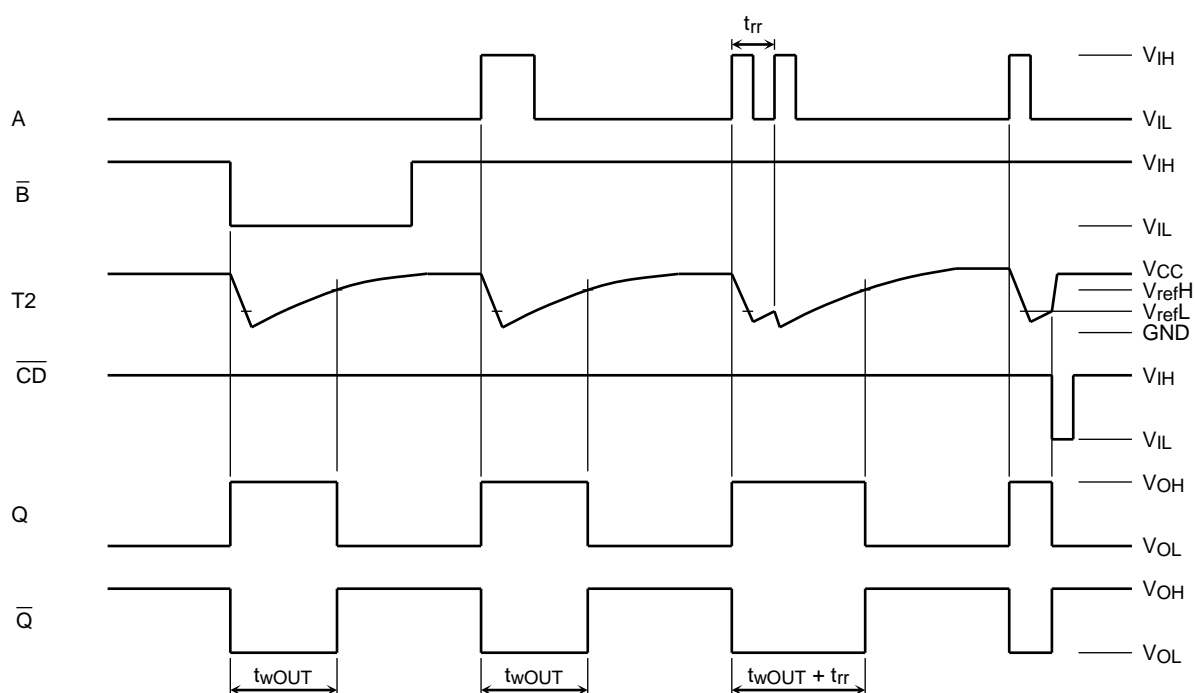
(t_f is the time from the voltage supply turning off to the level of supply voltage reaching 0.4 VCC.)

In the care of a system that does not satisfy the above condition, an external clamping diode is needed to protect the IC from rush current.

System Diagram



Timing Chart



Functional Description

(1) Stand-by state

The external capacitor is fully charge to V_{CC} in the stand-by state. That means, before triggering, QP and QN transistors which are connected to the T2 node are in the off state. Two comparators that relate to the timing of the output pulse, and two reference voltage supplies stop their operation. The total supply current is only leakage current.

(2) Trigger operation

Trigger operation is effective in either of the following two cases. One is the condition where the A input is low, and the \overline{B} input has a falling signal. The other, where the \overline{B} input is high, and the A input has a rising signal.

After trigger becomes effective, comparators C1 and C2 start operating, and QN is turned on. The external capacitor discharges through QN. The voltage level at the T2 node drops. If the T2 voltage level falls to the internal reference voltage V_{refL} , the output of C1 becomes low. The flip-flop is then reset and QN turns off. At that moment C1 stops but C2 continues operating.

After QN turns off, the voltage at T2 start rising at a rate determined by the time constant of external capacitor CX and resistor RX.

After the triggering, output Q becomes high, following some delay time of the internal F/F and gates. It stays high even if the voltage of T2 changes from falling to rising. When T2 reaches the internal reference voltage V_{refH} , the output of C2 becomes low, the output Q goes low and C2 stops its operation. That means, after triggering, when the voltage level of T2 reaches V_{refH} , the IC returns to its MONOSTABLE state.

In the case of large value of CX and RX, and ignoring the discharge time of the capacitor and internal delays of the IC, the width of the output pulse, (t_{wOUT}), is as follows:

$$t_{wOUT} = 0.70 \cdot C_X \cdot R_X$$

(3) Retrigger operation

When another new trigger is applied to input A or \overline{B} while in the MONOSTABLE state, it is effective only if the IC is charging CX. The voltage level of T2 then falls to V_{refL} level again.

Therefore the Q output stays high if the next trigger comes in before the time period set by CX and RX.

If the 2nd trigger is very close to previous trigger, such as application during the discharge cycle, the 2nd trigger will not be effective.

The minimum time for effective 2nd trigger, t_{rr} (min), depends on V_{CC} and CX.

(4) Reset operation

In normal operation, \overline{CD} input is held high. If \overline{CD} is low, a trigger has no effect because the Q output is held low and the trigger control F/F is reset. Also QP turns on and CX is charged rapidly to V_{CC} .

This means if \overline{CD} input is set low, the IC goes into a wait state.

Absolute Maximum Ratings (Note)

Characteristics	Symbol	Rating	Unit
Supply voltage range	V _{CC}	-0.5 to 7	V
DC input voltage	V _{IN}	-0.5 to V _{CC} + 0.5	V
DC output voltage	V _{OUT}	-0.5 to V _{CC} + 0.5	V
Input diode current	I _{IK}	±20	mA
Output diode current	I _{OK}	±20	mA
DC output current	I _{OUT}	±25	mA
DC V _{CC} /ground current	I _{CC}	±50	mA
Power dissipation	P _D	500 (DIP) (Note 1)/180 (SOP/TSSOP)	mW
Storage temperature	T _{stg}	-65 to 150	°C

Note: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Note 1: 500 mW in the range of T_a = -40°C to 65°C. From T_a = 65°C to 85°C a derating factor of -10 mW/°C should be applied up to 300 mW.

Operating Ranges (Note)

Characteristics	Symbol	Rating	Unit
Supply voltage	V _{CC}	2 to 6	V
Input voltage	V _{IN}	0 to V _{CC}	V
Output voltage	V _{OUT}	0 to V _{CC}	V
Operating temperature	T _{opr}	-40 to 85	°C
Input rise and fall time ($\overline{\text{CD}}$ only)	t _r , t _f	0 to 1000 (V _{CC} = 2.0 V) 0 to 500 (V _{CC} = 4.5 V) 0 to 400 (V _{CC} = 6.5 V)	ns
External capacitor	C _X	No limitation (Note 1)	F
External resistor	R _X	≥ 5 k (V _{CC} = 2.0 V) (Note 1) ≥ 1 k (V _{CC} ≥ 3.0 V) (Note 1)	Ω

Note: The operating ranges must be maintained to ensure the normal operation of the device. Unused inputs must be tied to either V_{CC} or GND.

Note 1: The maximum allowable values of C_X and R_X are a function of leakage of capacitor C_X, the leakage of TC74HC4538A, and leakage due to board layout and surface resistance. Susceptibility to externally induced noise signals may occur for R_X > 1 MΩ.

Electrical Characteristics
DC Characteristics

Characteristics	Symbol	Test Condition		Ta = 25°C			Ta = -40 to 85°C		Unit	
				VCC (V)	Min	Typ.	Max	Min		Max
High-level input voltage	V _{IH}	—		2.0 4.5 6.0	1.50 3.15 4.20	— — —	— — —	1.50 3.15 4.20	V	
Low-level input voltage	V _{IL}	—		2.0 4.5 6.0	— — —	— — —	0.50 1.35 1.80	— — —	V	
High-level output voltage (Q, \overline{Q})	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -20 μA	2.0	1.9	2.0	—	1.9	—	V
				4.5	4.4	4.5	—	4.4	—	
			I _{OH} = -4 mA I _{OH} = -5.2 mA	6.0	5.9	6.0	—	5.9	—	
				4.5	4.18	4.31	—	4.13	—	
Low-level output voltage (Q, \overline{Q})	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 20 μA	2.0	—	0.0	0.1	—	0.1	V
				4.5	—	0.0	0.1	—	0.1	
			I _{OL} = 4 mA I _{OL} = 5.2 mA	6.0	—	0.0	0.1	—	0.1	
				4.5	—	0.17	0.26	—	0.33	
Input leakage current	I _{IN}	V _{IN} = V _{CC} or GND	6.0	—	—	±0.1	—	±1.0	μA	
T2 terminal input leakage current	I _{IN}	V _{IN} = V _{CC} or GND	6.0	—	—	±0.5	—	±5.0	μA	
Quiescent supply current	I _{CC}	V _{IN} = V _{CC} or GND	6.0	—	—	4.0	—	40.0	μA	
Active-state supply current (Note 1)	I _{CC} '	V _{IN} = V _{CC} or GND R _X /C _X = 0.5 V _{CC}	2.0	—	40	120	—	160	μA	
			4.5	—	200	300	—	400		
			6.0	—	300	600	—	800		

Note 1: Per circuit

Timing Requirements (input: $t_r = t_f = 6 \text{ ns}$)

Characteristics	Symbol	Test Condition	Ta = 25°C		Ta = -40 to 85°C	Unit
			VCC (V)	Typ.	Max	
Minimum pulse width (A, \bar{B})	t_w (L) t_w (H)	—	2.0	—	75	95
			4.5	—	15	19
			6.0	—	13	16
Minimum clear width (\bar{CD})	t_w (L)	—	2.0	—	75	95
			4.5	—	15	19
			6.0	—	13	16
Minimum clear removal time	t_{rem}	—	2.0	—	15	15
			4.5	—	5	5
			6.0	—	5	5
Minimum retrigger time	t_{rr}	$R_X = 1 \text{ k}\Omega$ $C_X = 100 \text{ pF}$	2.0	380	—	—
			4.5	92	—	—
			6.0	72	—	—
		$R_X = 1 \text{ k}\Omega$ $C_X = 0.01 \text{ }\mu\text{F}$	2.0	6.0	—	—
			4.5	1.4	—	—
			6.0	1.2	—	—

AC Characteristics ($C_L = 15 \text{ pF}$, $V_{CC} = 5 \text{ V}$, $T_a = 25^\circ\text{C}$, input: $t_r = t_f = 6 \text{ ns}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Output transition time	t_{TLH}	—	—	6	12	ns
	t_{THL}					
Propagation delay time (A, \bar{B} -Q, \bar{Q})	t_{pLH}	—	—	25	44	ns
	t_{pHL}					
Propagation delay time (\bar{CD} -Q, \bar{Q})	t_{pLH}	—	—	21	34	ns
	t_{pHL}					

AC Characteristics (CL = 50 pF, input: tr = tf = 6 ns)

Characteristics	Symbol	Test Condition	Ta = 25°C			Ta = -40 to 85°C		Unit
			VCC (V)	Min	Typ.	Max	Min	Max
Output transition time	tTLH tTHL	—	2.0	—	30	75	—	95
			4.5	—	8	15	—	19
			6.0	—	7	13	—	16
Propagation delay time (A, \bar{B} -Q, \bar{Q})	tPLH tPHL	—	2.0	—	120	250	—	315
			4.5	—	30	50	—	63
			6.0	—	25	43	—	54
Propagation delay time (\bar{CD} -Q, \bar{Q})	tPLH tPHL	—	2.0	—	100	195	—	245
			4.5	—	25	39	—	49
			6.0	—	20	33	—	42
Output pulse width	twOUT	CX = 0 F RX = 5 kΩ (VCC = 2 V) RX = 1 kΩ (VCC = 4.5 V, 6 V)	2.0	—	540	1200	—	1500
			4.5	—	180	250	—	320
			6.0	—	150	200	—	260
		CX = 0.01 μF RX = 10 kΩ	2.0	70	83	96	70	96
			4.5	69	77	85	69	85
			6.0	69	77	85	69	85
		CX = 0.1 μF RX = 10 kΩ	2.0	0.67	0.75	0.83	0.67	0.83
			4.5	0.67	0.73	0.77	0.67	0.77
			6.0	0.67	0.73	0.77	0.67	0.77
Output pulse width error between circuits (in same package)	ΔtwOUT	—	—	—	±1	—	—	—
Input capacitance	CIN	—	—	—	5	10	—	10
Power dissipation capacitance	CPD	(Note 1)	—	—	70	—	—	—

Note 1: CPD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

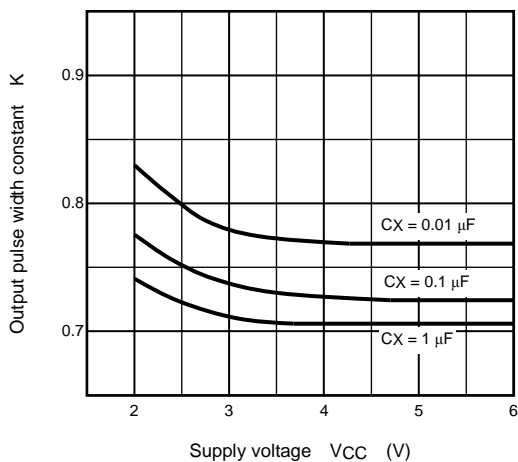
Average operating current can be obtained by the equation:

$$I_{CC} (opr) = CPD \cdot V_{CC} \cdot f_{IN} + I_{CC'} \cdot Duty/100 + I_{CC}/2 \text{ (per circuit)}$$

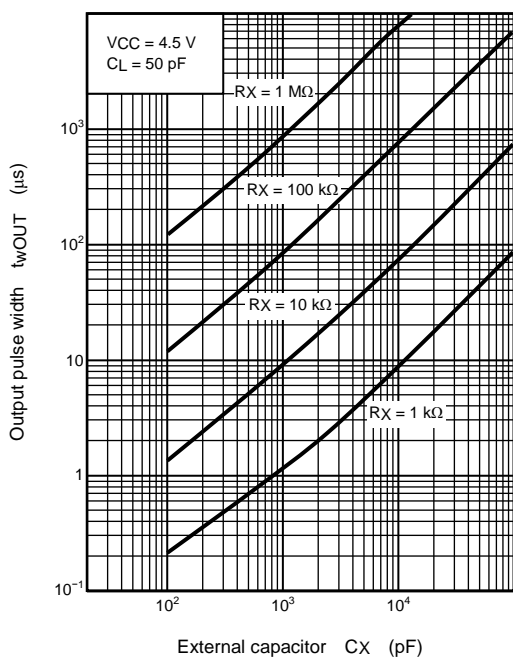
(ICC': active supply current)

(Duty: %)

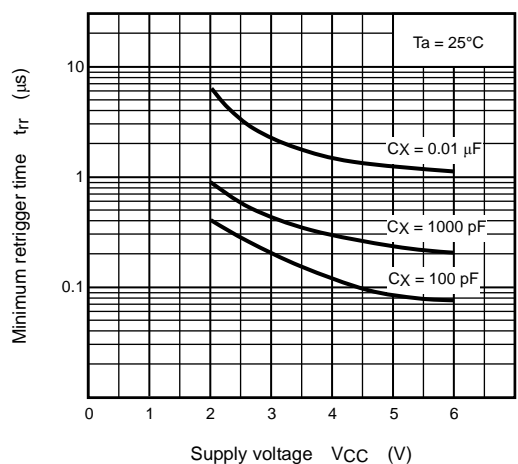
Output Pulse Width Constant K – Supply Voltage (typ.)
(external resistor (R_X) = 10 k Ω : $t_{wOUT} = K \cdot C_X \cdot R_X$)



$t_{wOUT} - C_X$ Characteristics (typ.)



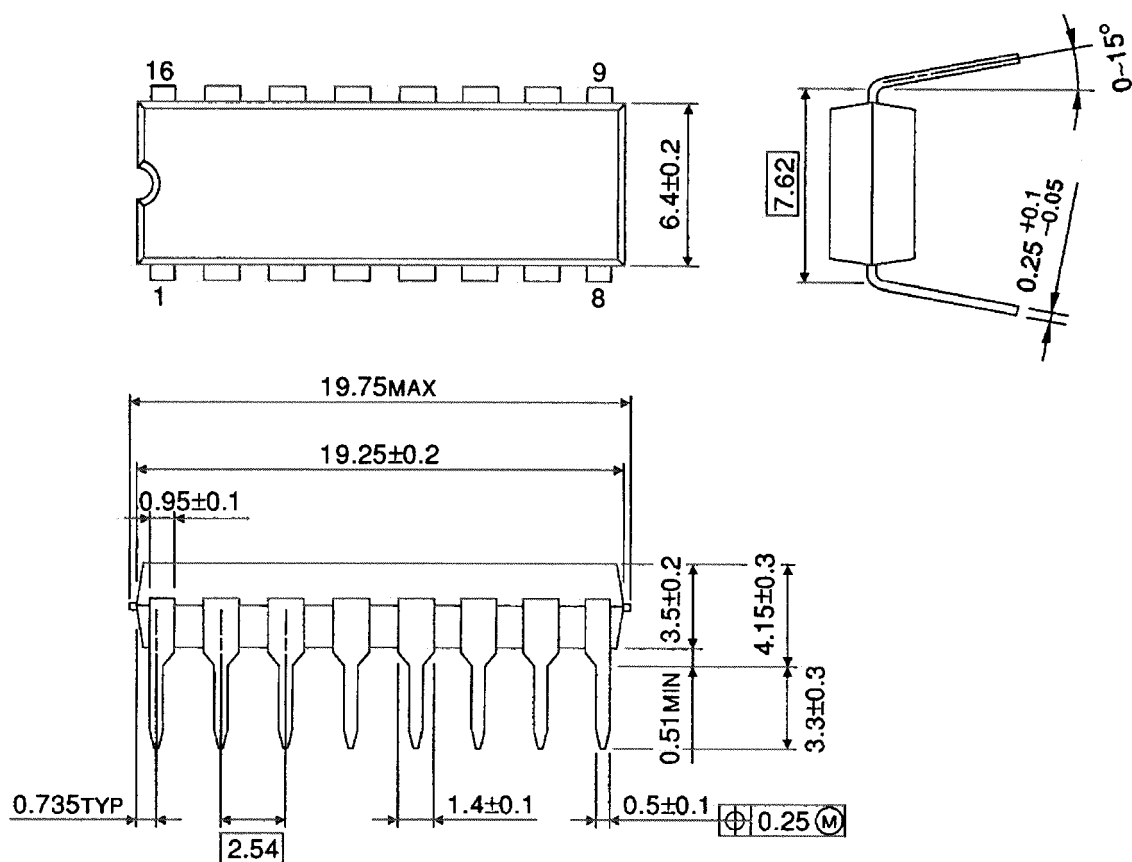
$t_{rr} - V_{CC}$ Characteristics (typ.)



Package Dimensions

DIP16-P-300-2.54A

Unit : mm

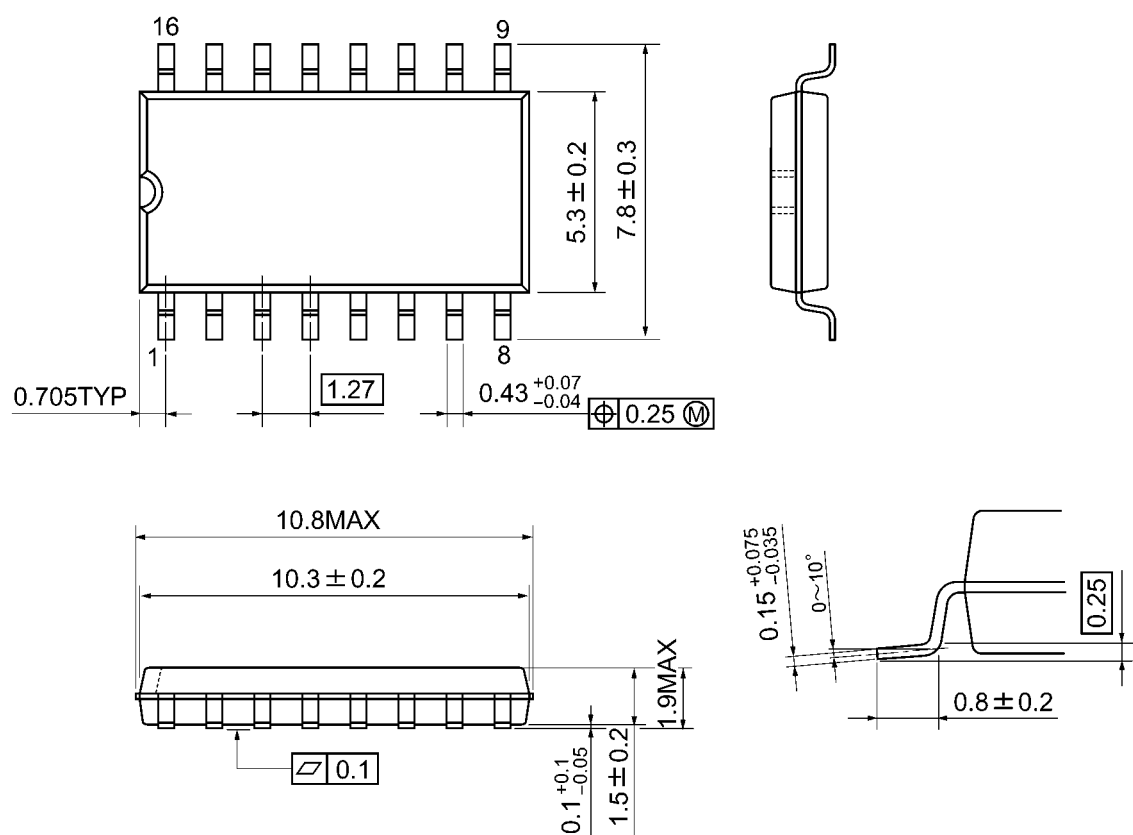


Weight: 1.00 g (typ.)

Package Dimensions

SOP16-P-300-1.27A

Unit: mm

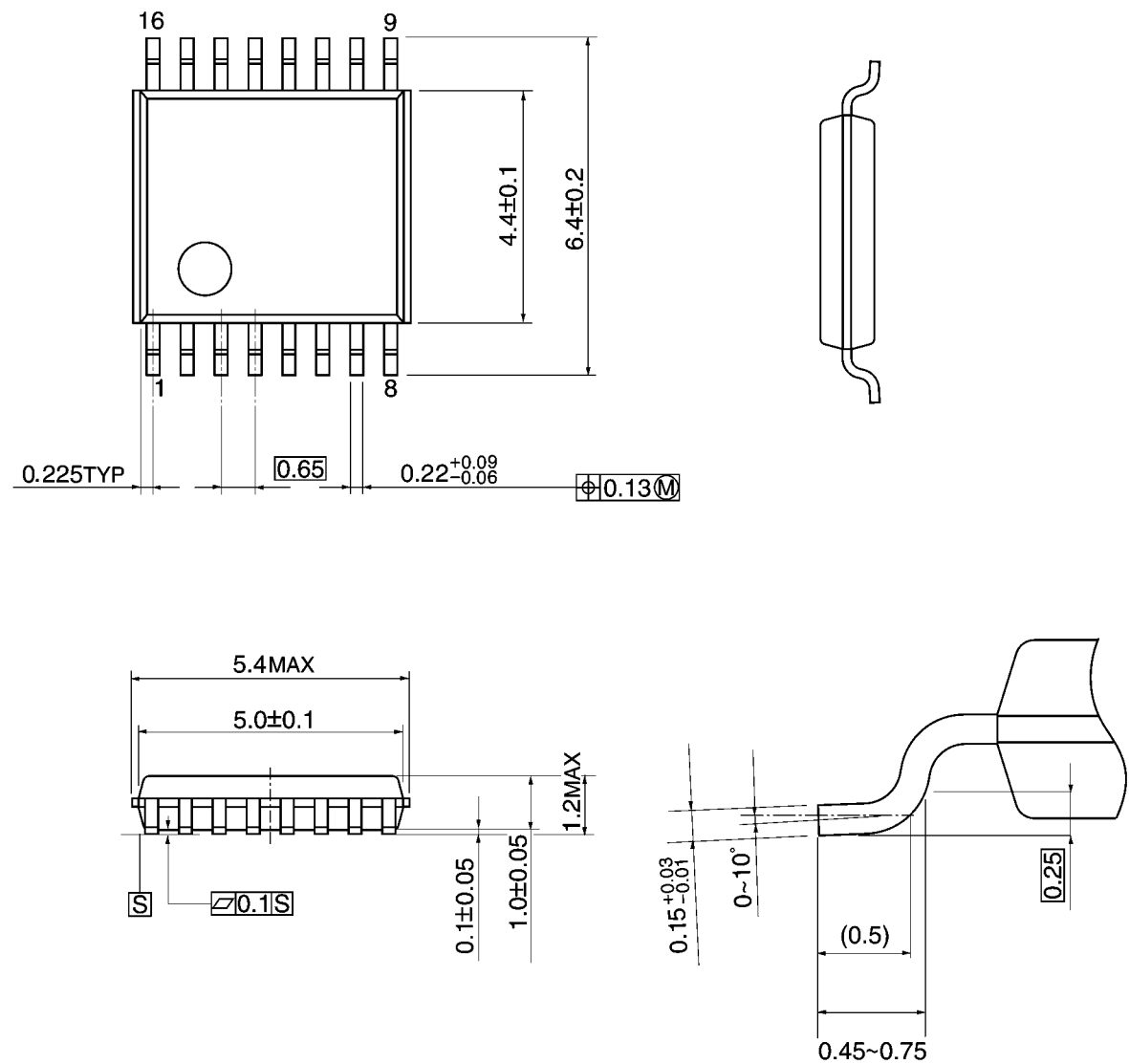


Weight: 0.18 g (typ.)

Package Dimensions

TSSOP16-P-0044-0.65A

Unit: mm



Weight: 0.06 g (typ.)

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